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U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office

Docket No.: 070679-0210

To the Director of the U. S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of Conveying Party(ies)

Joo-Ae LEE

Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of Conveyance/Execution Date(s)

Execution Date(s): December 21, 2006

- Assignment Merger
- Security Agreement Change of Name
- Joint Research Agreement
- Government Interest Assignment
- Executive Order 9424, Confirmatory License
- Other

2. Name and address of receiving party(ies)

Name: HYNIX SEMICONDUCTOR INC.

Internal Address:

Address: San 136-1, Ami-ri, Bubal-eub, Ichon-shi Kyoungki-do, 467-860 Republic of Korea

Additional name(s) & address(es) attached? Yes No

4. Application or patent number(s):

A. Patent Application No(s).

This document is being filed together with a new application.

B. Patent No(s).

Additional numbers attached? Yes No

5. Name and address to whom correspondence concerning document should be mailed:

Name: MCDERMOTT WILL & EMERY LLP

Internal Address:

Street Address: 600 13th Street, N.W.

City: Washington State: D. C. Zip: 20005-3096

Phone Number: 202.756.8000

Fax Number: 202.756.8087

Email Address:

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00

- Authorized to be charged by credit card
- Authorized to be charged to deposit account
- Enclosed
- None required (government interest not affecting title)nt

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9. Signature.

Stephen A. Becker, 26,527

Stephen A. Becker

December 29, 2006

Name and Registration No. of Person Signing

Signature

Date

Total number of pages including cover sheet, attachments and documents: 2

OMB No. 0651-0027 (exp. 6/30/2008)

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Docket No.: _____

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

LEE, Joo-Ae

who has made a certain new and useful invention, hereby sells, assigns and transfers unto
Hynix Semiconductor Inc.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled
SEMICONDUCTOR MEMORY DEVICE

(a) for which an application for United States Letters Patent was filed on _____, and identified by United States Serial No. _____; or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:
INVENTOR

DATE SIGNED

LEE, Joo-Ae

December 21 , 2006

Name: **LEE, Joo-Ae**